

## EAST Search History

Ref #	Hits	Search Query	DBs	Default Operator	Plurals	Time Stamp
L1	0	"2001041381".pn. or "2001055146".pn. or "2002195673".pn.	US-PGPUB; USPAT	OR	OFF	2006/12/15 10:55
L2	3	"20010041381".pn. or "20010055146".pn. or "20020195673".pn.	US-PGPUB; USPAT	OR	OFF	2006/12/15 10:56
L3	66	wafer\$4 same solder\$4 same (reflect\$4 or mirror\$4) same electro\$4	US-PGPUB; USPAT	OR	ON	2006/12/15 11:06
L4	43	(wafer\$4 same microstructu\$4 same electro\$4 same (mirror\$4 or reflect\$4))	US-PGPUB; USPAT	OR	ON	2006/12/15 11:06
L5	2629	(wafer\$4 same electro\$4 same (mirror\$4 or reflect\$4))	US-PGPUB; USPAT	OR	OFF	2006/12/15 11:06
L6	101	L5 and 385/16-18.ccls.	US-PGPUB; USPAT	OR	ON	2006/12/15 11:06
L7	2629	(wafer\$4 same electro\$4 same (mirror\$4 or reflect\$4))	US-PGPUB; USPAT	OR	ON	2006/12/15 11:07
L8	966	(chip and bond\$4 and (interconnect\$4 connect\$4) and electri\$4 and terminal\$4).clm.	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2006/12/15 11:07
L9	9	(chip and bond\$4 and (interconnect\$4 connect\$4) and electri\$4 and terminal\$4 and (fiber\$4 fibre\$4) and pattern).clm.	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2006/12/15 11:08
L10	42	(chip and bond\$4 and (interconnect\$4 connect\$4) and electri\$4 and terminal\$4 and (fiber\$4 fibre\$4)).clm.	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2006/12/15 11:08
S1	47	wafer\$4 same solder\$4 same (reflect\$4 or mirror\$4) same electro\$4	US-PGPUB; USPAT	OR	OFF	2006/12/15 11:06
S2	0	(wafer\$4 same microstructu\$4 same electro\$4) and 385/16-18.ccls.	US-PGPUB; USPAT	OR	OFF	2005/05/27 07:53
S3	2	(wafer\$4 same microstructu\$4 same electro\$4) and 385/16-18.ccls.	US-PGPUB; USPAT	OR	OFF	2005/11/16 18:04
S4	118	(wafer\$4 same microstructu\$4 same electro\$4)	US-PGPUB; USPAT	OR	OFF	2005/05/27 07:55

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S5	22	(wafer\$4 same microstructu\$4 same electrod\$4 same (mirror\$4 or reflect\$4))	US-PGPUB; USPAT	OR	OFF	2006/12/15 11:06
S6	2045	(wafer\$4 same electrod\$4 same (mirror\$4 or reflect\$4))	US-PGPUB; USPAT	OR	OFF	2005/05/27 12:58
S7	81	S6 and 385/16-18.ccls.	US-PGPUB; USPAT	OR	OFF	2006/12/15 11:06
S8	80	S7 not S5	US-PGPUB; USPAT	OR	OFF	2005/11/16 18:05
S9	144719	"8" and solder\$4	US-PGPUB; USPAT	OR	OFF	2005/05/27 12:57
S10	23	(wafer\$4 same electrod\$4 same (mirror\$4 or reflect\$4)) and solder\$4 and 385/16-18.ccls.	US-PGPUB; USPAT	OR	OFF	2005/11/16 14:57
S11	793	wafer same solder\$4 same ((flip\$ or chip\$4 or bond\$4) and adhesive)	US-PGPUB; USPAT	OR	OFF	2005/11/16 14:41
S12	84	wafer same solder\$4 same ((flip\$ with chip\$4 with bond\$4) and adhesive)	US-PGPUB; USPAT	OR	OFF	2005/11/16 14:41
S13	58	wafer\$4 same solder\$4 same (reflect\$4 or mirror\$4) same electrod\$4	US-PGPUB; USPAT	OR	OFF	2006/08/13 14:04
S14	36	(wafer\$4 same microstructu\$4 same electrod\$4 same (mirror\$4 or reflect\$4))	US-PGPUB; USPAT	OR	OFF	2005/11/16 18:09
S15	28	(wafer\$4 same electrod\$4 same (mirror\$4 or reflect\$4)) and solder\$4 and 385/16-18.ccls.	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	OFF	2005/11/16 18:07
S16	106	wafer\$4 same solder\$4 same (reflect\$4 or mirror\$4) same electrod\$4	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	OFF	2005/11/16 18:04
S17	3	(wafer\$4 same microstructu\$4 same electrod\$4) and 385/16-18.ccls.	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	OFF	2005/11/16 18:04
S18	36	(wafer\$4 same microstructu\$4 same electrod\$4 same (mirror\$4 or reflect\$4))	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	OFF	2005/11/16 18:05

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S19	36	(wafer\$4 same microstructu\$4 same electro\$4 same (mirror\$4 or reflect\$4))	US-PGPUB; USPAT	OR	OFF	2005/11/16 18:07
S20	2239	(wafer\$4 same electro\$4 same (mirror\$4 or reflect\$4))	US-PGPUB; USPAT	OR	OFF	2005/11/16 18:07
S21	90	S20 and 385/16-18.ccls.	US-PGPUB; USPAT	OR	OFF	2005/11/16 18:07
S22	88	S21 not S19	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	OFF	2005/11/16 18:07
S23	28	(wafer\$4 same electro\$4 same (mirror\$4 or reflect\$4)) and solder\$4 and 385/16-18.ccls.	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	OFF	2005/11/16 18:09
S24	36	(wafer\$4 same microstructu\$4 same electro\$4 same (mirror\$4 or reflect\$4))	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	OFF	2005/11/16 18:10
S25	812	(chip and bond\$4 and (interconnect\$4 connect\$4) and electri\$4 and terminal\$4).clm.	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	OFF	2006/12/15 11:07
S26	32	(chip and bond\$4 and (interconnect\$4 connect\$4) and electri\$4 and terminal\$4 and (fiber\$4 fibre\$4)).clm.	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	OFF	2006/12/15 11:08
S27	4	(chip and bond\$4 and (interconnect\$4 connect\$4) and electri\$4 and terminal\$4 and (fiber\$4 fibre\$4) and pattern).clm.	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	OFF	2006/12/15 11:08
S28	0	lin.xa. and tina.xa. and lens and bulge	US-PGPUB; USPAT	OR	OFF	2005/11/16 18:51
S29	42	lin.xa. and tina.xa. and lens	US-PGPUB; USPAT	OR	OFF	2005/11/16 18:51

## EAST Search History

S30	251	solder\$4 same wafer\$4 same optic\$3 same (electronic or electri\$4)	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2006/03/24 15:42
S31	356	wafer\$4 same solder\$4 same lower same upper	US-PGPUB; USPAT	OR	OFF	2006/03/28 14:46
S32	1	"6525864".pn.	US-PGPUB; USPAT	OR	OFF	2006/03/28 15:10
S33	1	"6781208".pn.	US-PGPUB; USPAT	OR	OFF	2006/03/28 15:11
S34	1	"6781239".pn.	US-PGPUB; USPAT	OR	OFF	2006/03/28 15:12
S35	1	"6946321".pn.	US-PGPUB; USPAT	OR	OFF	2006/03/28 15:13
S36	4	"5757536".pn. "20030122206".pn. "5096279".pn. "20020110312".pn.	US-PGPUB; USPAT	OR	OFF	2006/08/13 14:03
S37	64	wafer\$4 same solder\$4 same (reflect\$4 or mirror\$4) same electrodd\$4	US-PGPUB; USPAT	OR	ON	2006/08/13 14:04
S38	2516	(wafer\$4 same electrodd\$4 same (mirror\$4 or reflect\$4))	US-PGPUB; USPAT	OR	OFF	2006/08/13 14:04
S39	98	S38 and 385/16-18.ccls.	US-PGPUB; USPAT	OR	ON	2006/08/13 14:04
S40	64	wafer\$4 same solder\$4 same (reflect\$4 or mirror\$4) same electrodd\$4	US-PGPUB; USPAT	OR	ON	2006/08/13 14:04
S41	3218	wafer\$4 same (reflect\$4 or mirror\$4) same electrodd\$4	US-PGPUB; USPAT; USOCR; FPRS; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2006/08/13 16:21
S42	812	(wafer\$4 same (reflect\$4 or mirror\$4) same electrodd\$4) and ((solder\$4 contact\$4) with wafer\$4)	US-PGPUB; USPAT; USOCR; FPRS; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2006/08/13 16:22
S43	14	("5083857"   "5435876"   "5492596"   "5798557"   "5915168"   "6063696"   "6117705"   "6228684"   "6285064"   "6428650"   "6531328"   "6613607"   "6660562"   "6759723").PN. OR ("6908791").URPN.	US-PGPUB; USPAT; USOCR	OR	ON	2006/08/13 16:45